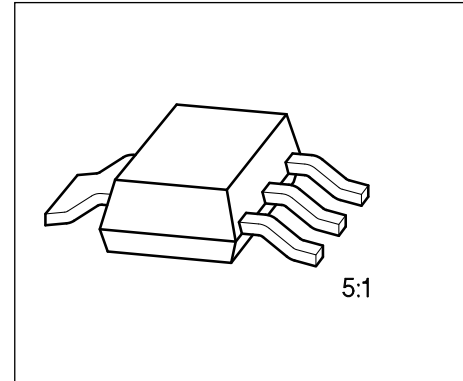


- $V_{DS}$  50 V
- $I_D$  3.2 A
- $R_{DS(on)}$  0.1  $\Omega$
- N channel
- Enhancement mode
- Avalanche rated



Type	Ordering Code	Tape and Reel Information	Pin Configuration				Marking	Package
			1	2	3	4		
BSP 17	Q67000-S220	E6327: 1000 pcs/reel	G	D	S	D	BSP 17	SOT-223

### Maximum Ratings

Parameter	Symbol	Values	Unit	
Gate-source voltage	$V_{GS}$	$\pm 20$	V	
Continuous drain current, $T_A = 27^\circ\text{C}$	$I_D$	3.2	A	
Pulsed drain current, $T_A = 25^\circ\text{C}$	$I_{D\text{ puls}}$	12.8		
Avalanche current, limited by $T_{j\text{ max}}$	$I_{AR}$	3.2		
Avalanche energy, periodic limited by $T_{j\text{ max}}$	$E_{AR}$	1	mJ	
Avalanche energy, single pulse $I_D = 3.2\text{ A}$ , $V_{DD} = 25\text{ V}$ , $R_{GS} = 25\ \Omega$ $L = 586\ \mu\text{H}$ , $T_j = 25^\circ\text{C}$	$E_{AS}$	6		
Max. power dissipation, $T_A = 25^\circ\text{C}$	$P_{\text{tot}}$	1.8	W	
Operating and storage temperature range	$T_j, T_{\text{stg}}$	$-55 \dots +150$	$^\circ\text{C}$	
Thermal resistance <sup>1)</sup>	chip-ambient	$R_{\text{thJA}}$	70	K/W
	chip-soldering point	$R_{\text{thJS}}$	6	
DIN humidity category, DIN 40 040	–	E	–	
IEC climatic category, DIN IEC 68-1	–	55/150/56	–	

<sup>1)</sup> Transistor on epoxy pcb 40 mm × 40 mm × 1.5 mm with 6 cm<sup>2</sup> copper area for drain connection.

## Electrical Characteristics

at  $T_j = 25\text{ °C}$ , unless otherwise specified.

Parameter	Symbol	Values			Unit
		min.	typ.	max.	

### Static Characteristics

Drain-source breakdown voltage $V_{GS} = 0, I_D = 0.25\text{ mA}$	$V_{(BR)DSS}$	50	–	–	V
Gate threshold voltage $V_{GS} = V_{DS}, I_D = 1\text{ mA}$	$V_{GS(th)}$	2.1	3.0	4.0	
Zero gate voltage drain current $V_{DS} = 50\text{ V}, V_{GS} = 0$ $T_j = 25\text{ °C}$ $T_j = 125\text{ °C}$	$I_{DSS}$	– –	0.1 10	1.0 100	$\mu\text{A}$
Gate-source leakage current $V_{GS} = 20\text{ V}, V_{DS} = 0$	$I_{GSS}$	–	10	100	nA
Drain-source on-resistance $V_{GS} = 10\text{ V}, I_D = 3.2\text{ A}$	$R_{DS(on)}$	–	0.09	0.1	$\Omega$

### Dynamic Characteristics

Forward transconductance $V_{DS} \geq 2 \times I_D \times R_{DS(on)max}, I_D = 3.2\text{ A}$	$g_{fs}$	2.5	5.2	–	S
Input capacitance $V_{GS} = 0, V_{DS} = 25\text{ V}, f = 1\text{ MHz}$	$C_{iss}$	–	450	600	$\mu\text{F}$
Output capacitance $V_{GS} = 0, V_{DS} = 25\text{ V}, f = 1\text{ MHz}$	$C_{oss}$	–	220	350	
Reverse transfer capacitance $V_{GS} = 0, V_{DS} = 25\text{ V}, f = 1\text{ MHz}$	$C_{rss}$	–	85	150	
Turn-on time $t_{on}$ , ( $t_{on} = t_{d(on)} + t_r$ ) $V_{DD} = 30\text{ V}, V_{GS} = 10\text{ V}, R_{GS} = 50\text{ }\Omega, I_D = 3\text{ A}$	$t_{d(on)}$	–	20	30	ns
	$t_r$	–	40	60	
Turn-off time $t_{off}$ , ( $t_{off} = t_{d(off)} + t_f$ ) $V_{DD} = 30\text{ V}, V_{GS} = 10\text{ V}, R_{GS} = 50\text{ }\Omega, I_D = 3\text{ A}$	$t_{d(off)}$	–	55	70	
	$t_f$	–	40	55	

## Electrical Characteristics (cont'd)

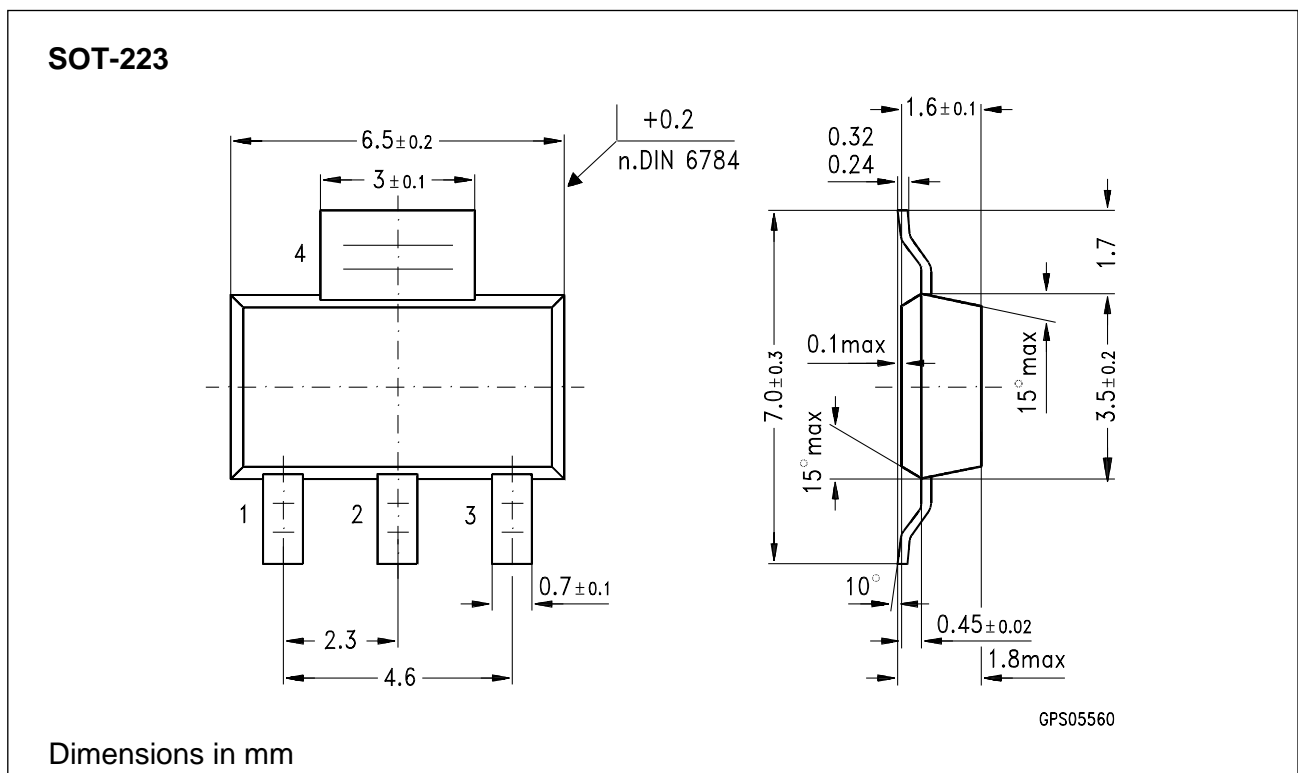
at  $T_j = 25\text{ °C}$ , unless otherwise specified.

Parameter	Symbol	Values			Unit
		min.	typ.	max.	

### Reverse Diode

Continuous reverse drain current	$I_S$	–	–	3.2	A
Pulsed source current	$I_{SM}$	–	–	12.8	
Diode forward on-voltage $I_F = 6.4\text{ A}$ , $V_{GS} = 0$	$V_{SD}$	–	1.05	1.2	V
Reverse recovery time $V_R = 30\text{ V}$ , $I_F = I_S$ , $di_F/dt = 100\text{ A}/\mu\text{s}$	$t_{rr}$	–	40	–	ns
Reverse recovery charge $V_R = 30\text{ V}$ , $I_F = I_S$ , $di_F/dt = 100\text{ A}/\mu\text{s}$	$Q_{rr}$	–	0.04	–	$\mu\text{C}$

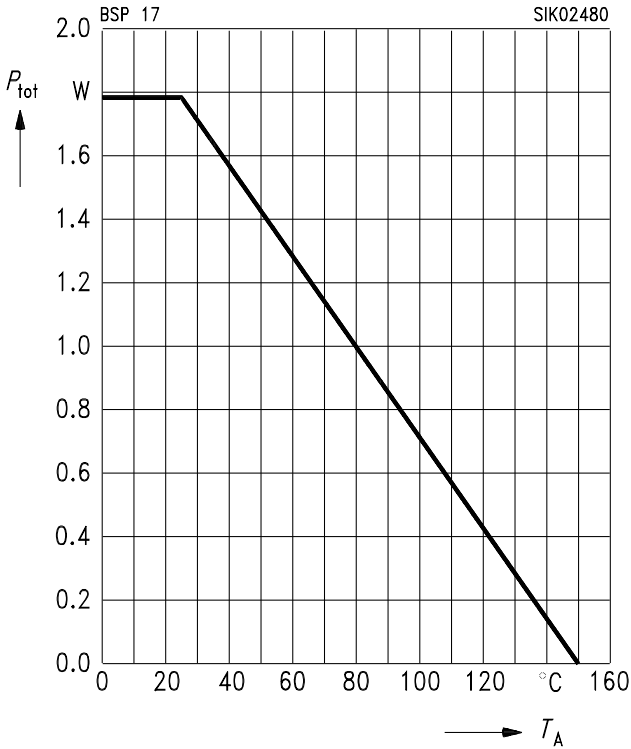
### Package Outline



**Characteristics**

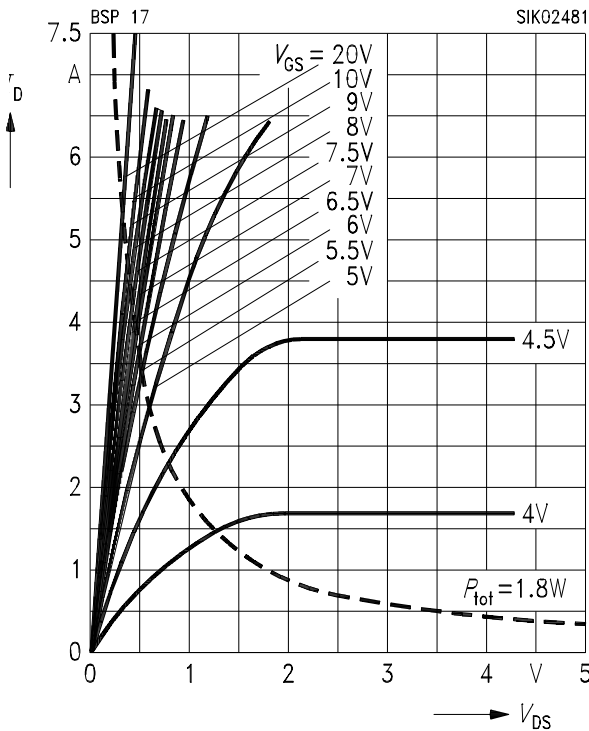
at  $T_j = 25\text{ }^\circ\text{C}$ , unless otherwise specified.

**Total power dissipation  $P_{\text{tot}} = f(T_A)$**



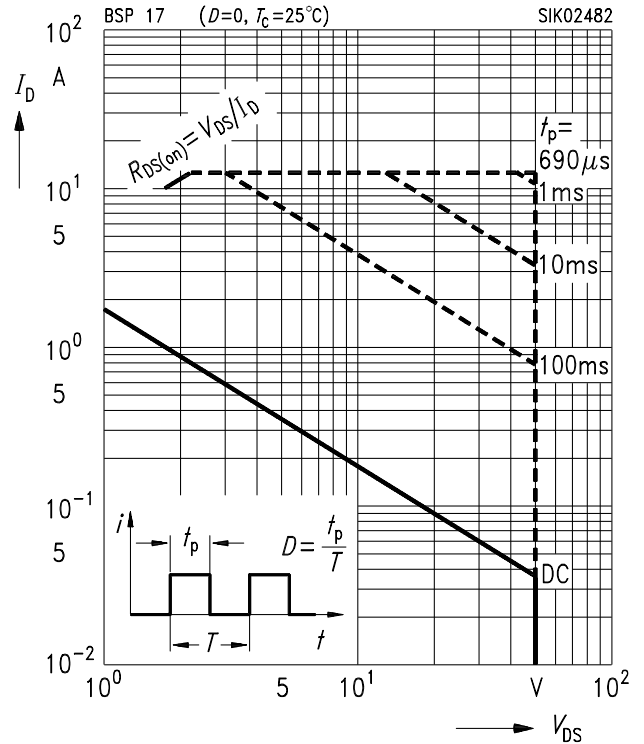
**Typ. output characteristics  $I_D = f(V_{\text{DS}})$**

parameter:  $t_p = 80\text{ }\mu\text{s}$



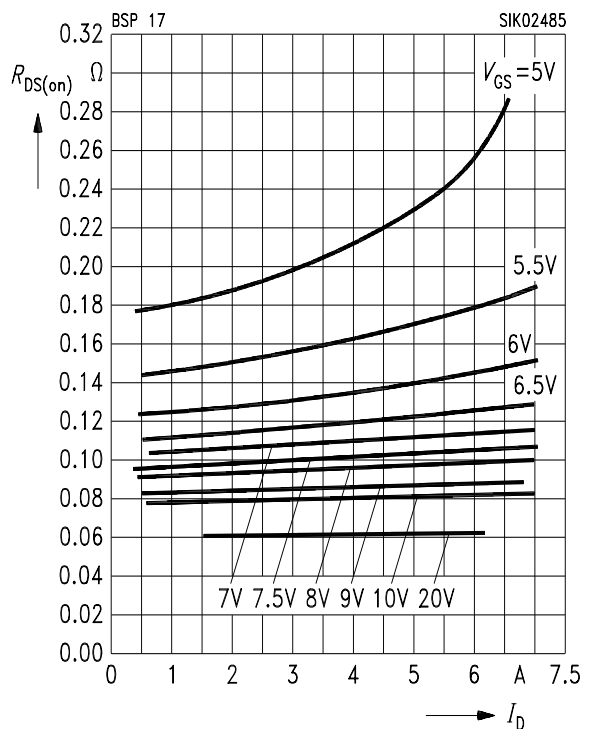
**Safe operating area  $I_D = f(V_{\text{DS}})$**

parameter:  $D = 0, T_c = 25\text{ }^\circ\text{C}$

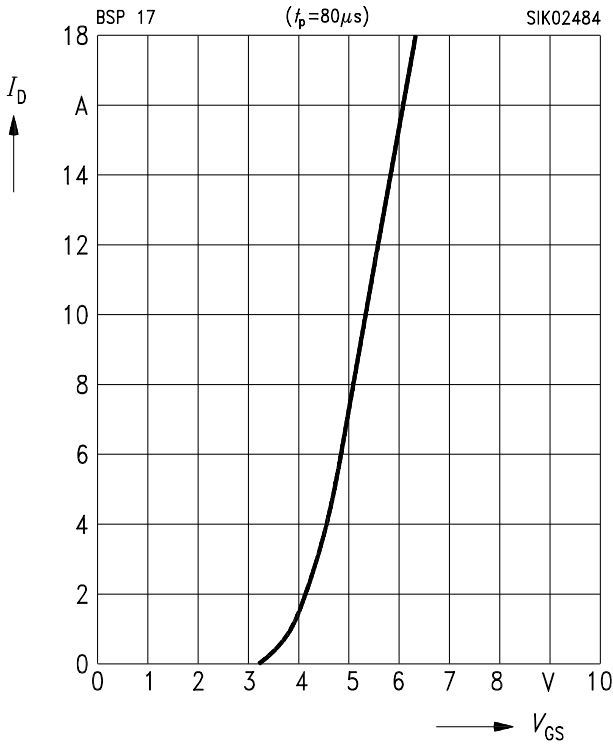


**Typ. drain-source on-resistance  $R_{\text{DS(on)}} = f(I_D)$**

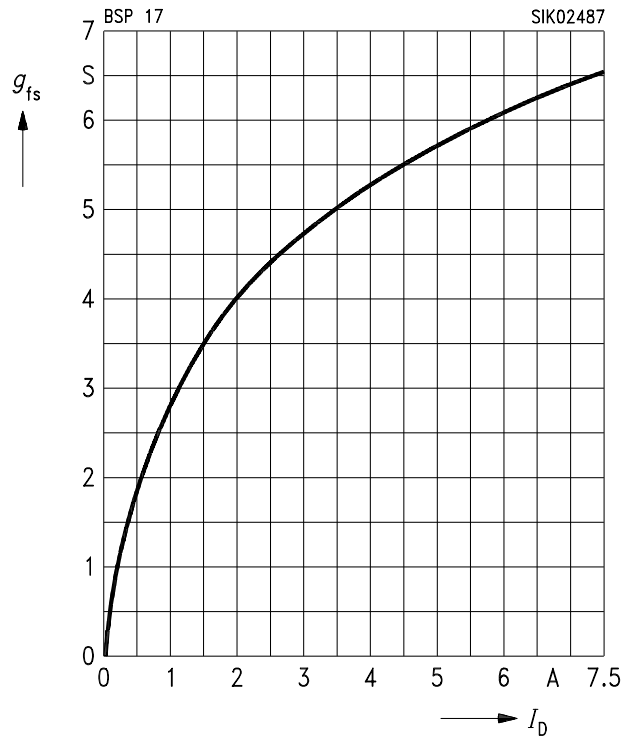
parameter:  $V_{\text{GS}}$



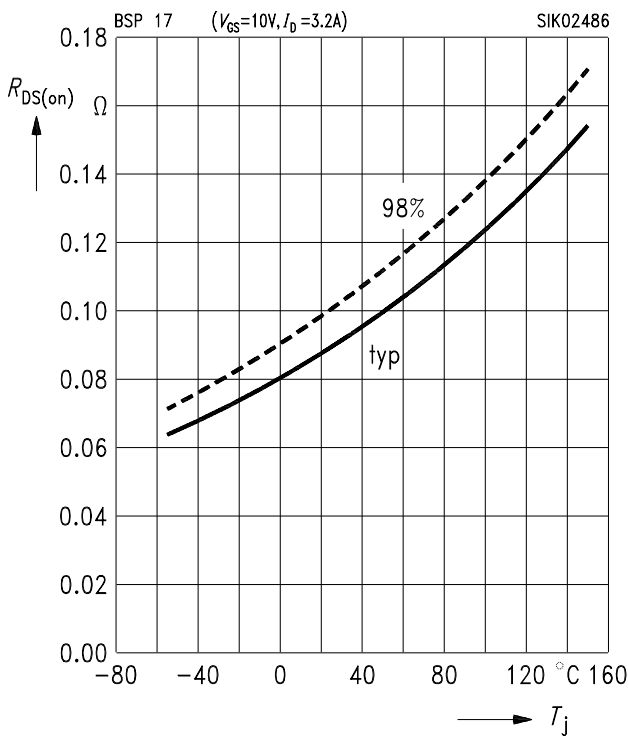
**Typ. transfer characteristics**  $I_D = f(V_{GS})$   
 parameter:  $t_p = 80 \mu s$ ,  $V_{DS} \geq 2 \times I_D \times R_{DS(on)max}$



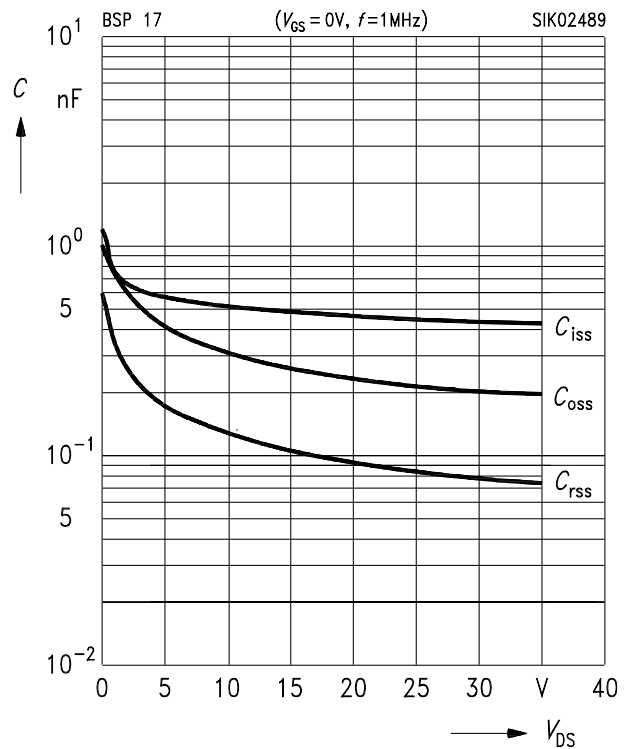
**Typ. forward transconductance**  $g_{fs} = f(I_D)$   
 parameter:  $V_{DS} \geq 2 \times I_D \times R_{DS(on)max}$ ,  $t_p = 80 \mu s$



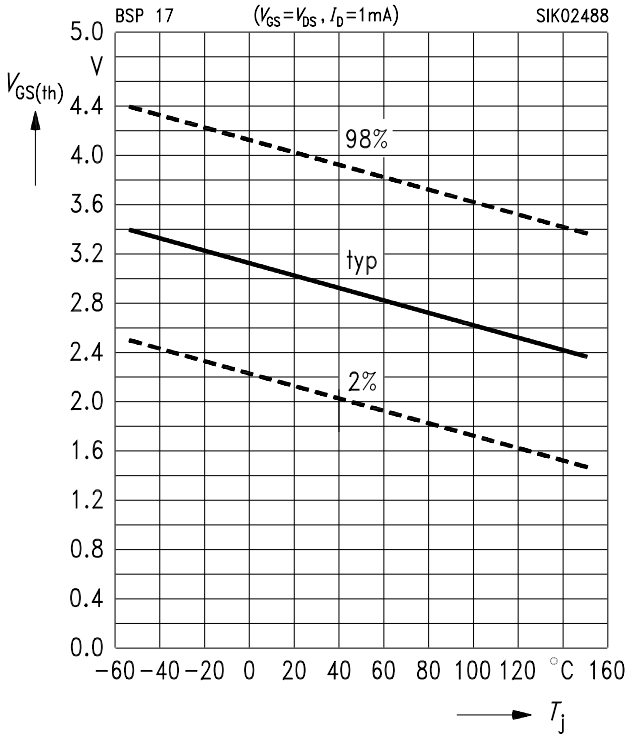
**Drain-source on-resistance**  
 $R_{DS(on)} = f(T_j)$   
 parameter:  $I_D = 3.2 A$ ,  $V_{GS} = 10 V$ , (spread)



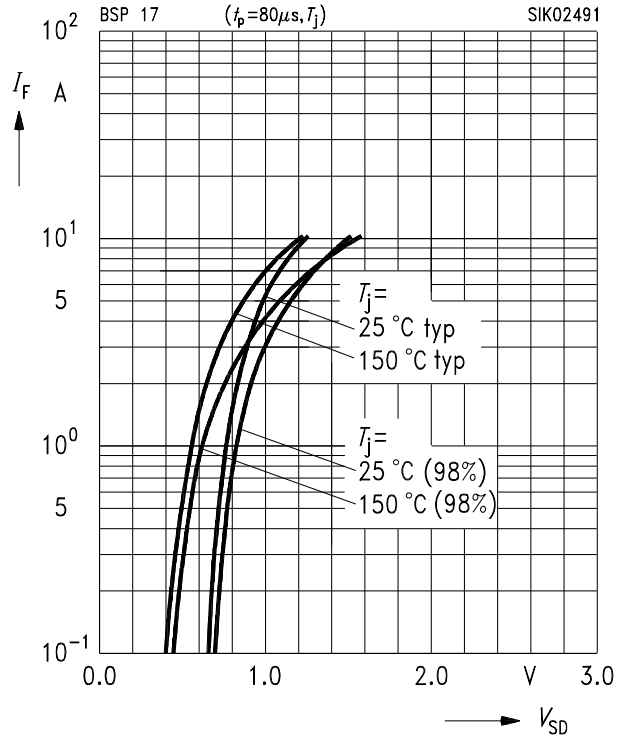
**Typ. capacitances**  $C = f(V_{DS})$   
 parameter:  $V_{GS} = 0V$ ,  $f = 1 MHz$



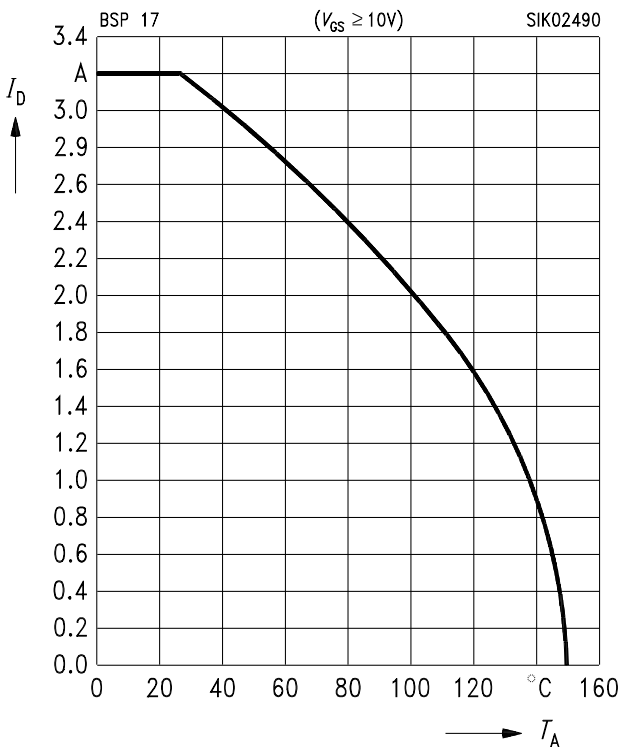
**Gate threshold voltage**  $V_{GS(th)} = f(T_j)$   
 parameter:  $V_{DS} = V_{GS}$ ,  $I_D = 1 \text{ mA}$ , (spread)



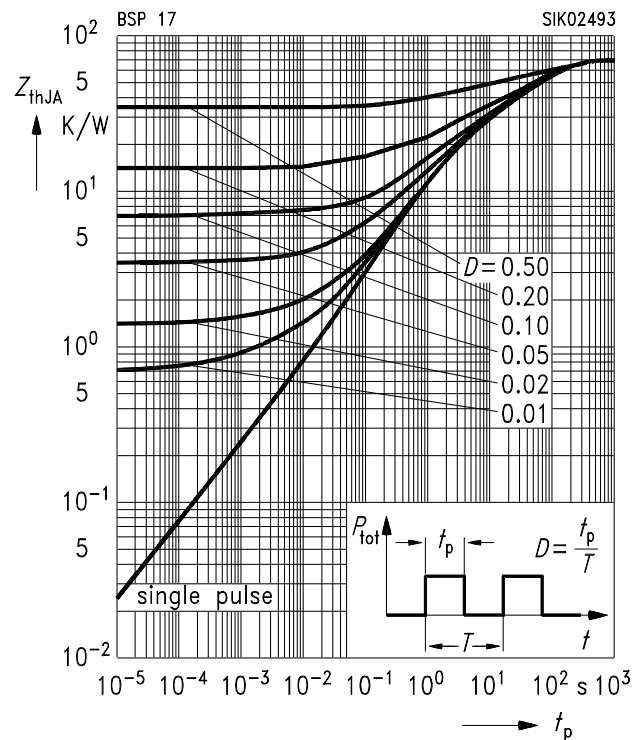
**Forward characteristics of reverse diode**  
 $I_F = f(V_{SD})$   
 parameter:  $t_p = 80 \mu\text{s}$ ,  $T_j$ , (spread)



**Drain current**  $I_D = f(T_A)$   
 parameter:  $V_{GS} \geq 10 \text{ V}$

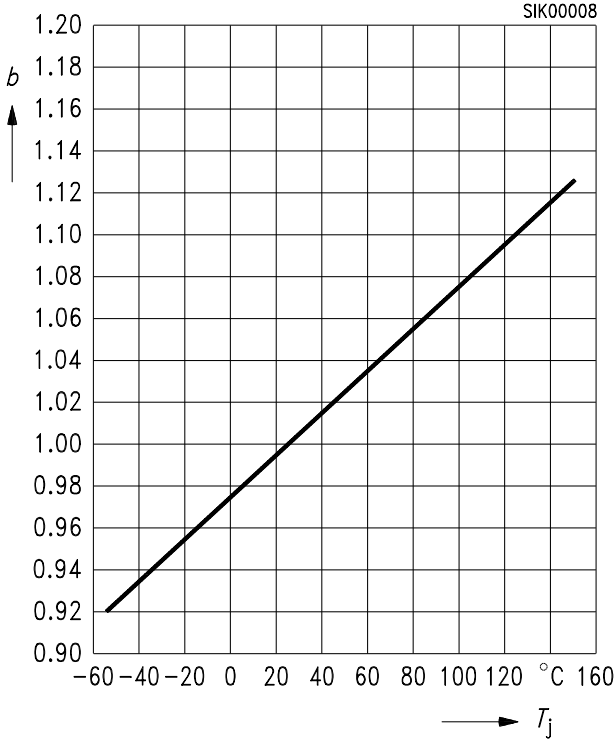


**Transient thermal impedance**  $Z_{thJA} = f(t_p)$   
 parameter:  $D = t_p / T$



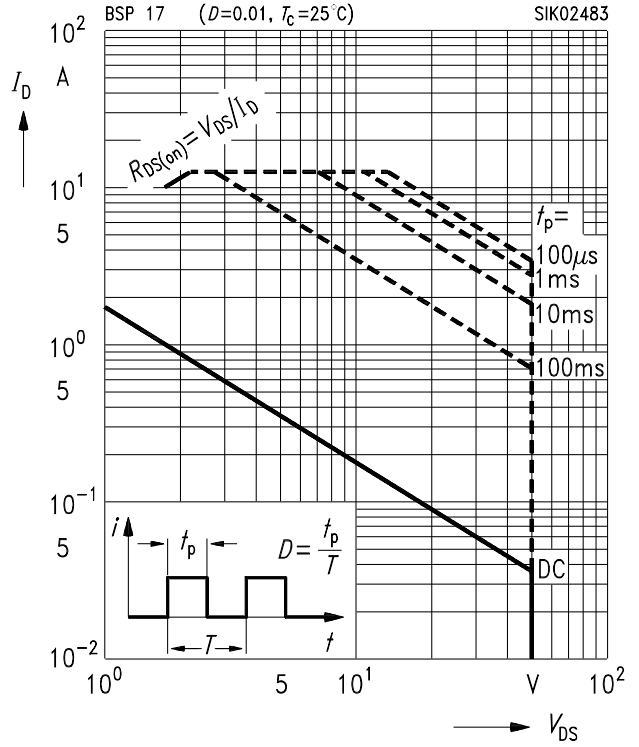
**Drain-source breakdown voltage**

$V_{(BR)DSS} = b \times V_{(BR)DSS} (25\text{ }^\circ\text{C})$



**Safe operating area  $I_D = f(V_{DS})$**

parameter:  $D = 0.01, T_C = 25\text{ }^\circ\text{C}$



**Avalanche energy  $E_{AS} = f(T_j)$**

parameter:  $I_D = 3.2\text{ A}, V_{DD} = 25\text{ V},$

$R_{GS} = 25\text{ }\Omega, L = 586\text{ }\mu\text{H}$

